- **Each Device Drives Ten Lines**
- **60-V Output Voltage Rating**
- **40-mA Output Source Current**
- **High-Speed Serially-Shifted Data Input**
- **CMOS-Compatible Inputs**
- **Latches on All Driver Outputs**
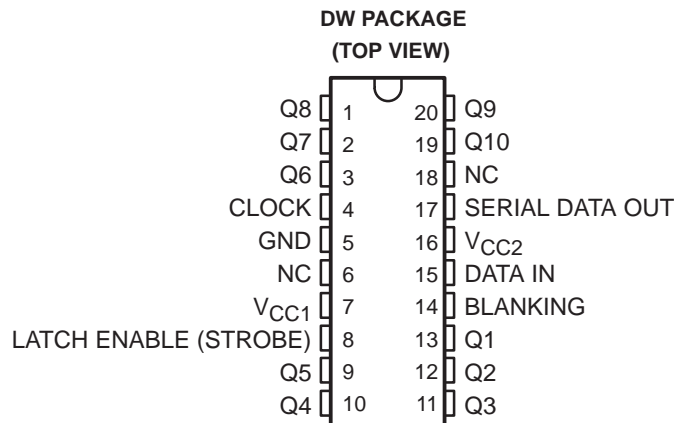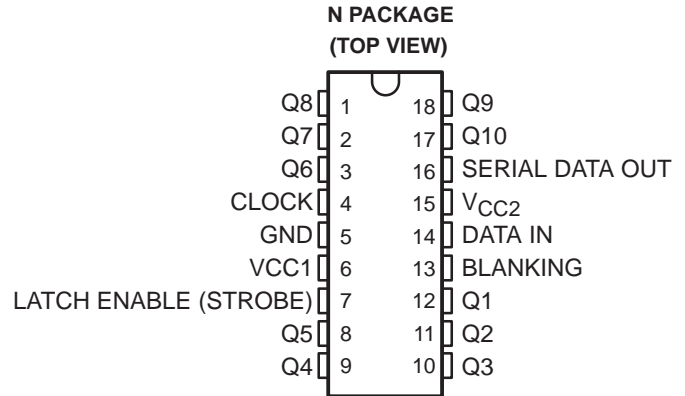- **Improved Direct Replacement for UCN4810A and TL4810A**

description

The TL4810B and TL4810BI are monolithic BIDFET† integrated circuits designed to drive a dot matrix or segmented vacuum fluorescent display (VFD). These devices feature a serial data output to cascade additional devices for large display arrays.

A 10-bit data word is serially loaded into the shift register on the positive-going transitions of the clock. Parallel data is transferred to the output buffers through a 10-bit D-type latch while LATCH ENABLE is high and is latched when LATCH ENABLE is low. When BLANKING is high, all outputs are low.

Outputs are totem-pole structures formed by npn emitter-follower and double-diffused MOS (DMOS) transistors with output voltage ratings of 70 V and 40-mA source-current capability. All inputs are compatible with CMOS and TTL levels, but each requires the addition of a pullup resistor to V_{CC1} when driven by TTL logic.

The TL4810B is characterized for operation from 0°C to 70°C. The TL4810BI is characterized for operation from −40°C to 85°C.
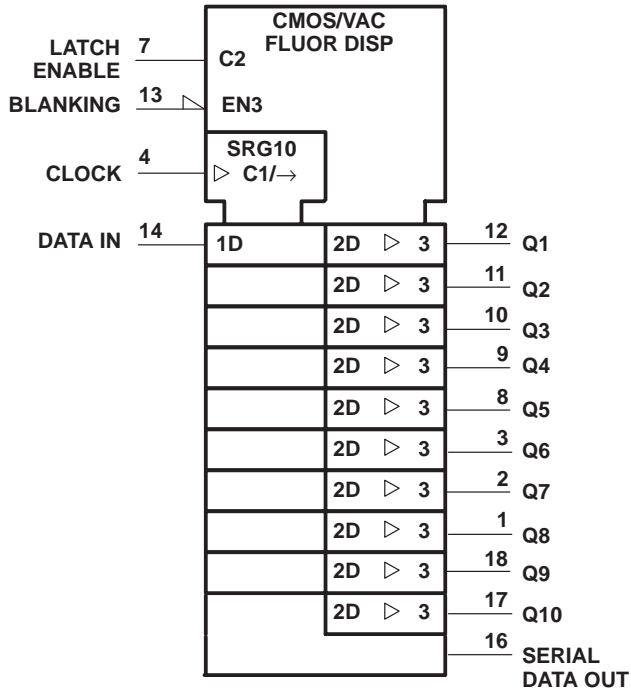
N PACKAGE
(TOP VIEW)

Q8	1	18	Q9
Q7	2	17	Q10
Q6	3	16	SERIAL DATA OUT
CLOCK	4	15	V_{CC2}
GND	5	14	DATA IN
VCC1	6	13	BLANKING
LATCH ENABLE (STROBE)	7	12	Q1
Q5	8	11	Q2
Q4	9	10	Q3

DW PACKAGE
(TOP VIEW)

Q8	1	20	Q9
Q7	2	19	Q10
Q6	3	18	NC
CLOCK	4	17	SERIAL DATA OUT
GND	5	16	V_{CC2}
NC	6	15	DATA IN
V_{CC1}	7	14	BLANKING
LATCH ENABLE (STROBE)	8	13	Q1
Q5	9	12	Q2
Q4	10	11	Q3

NC – No internal connection

† BIDFET – Bipolar, double-diffused, N-channel and P-channel MOS transistors on same chip. This is a patented process.

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TL4810B, TL4810BI
VACUUM FLUORESCENT DISPLAY DRIVERS

SLDS006C – DECEMBER 1984 – REVISED MAY 1993
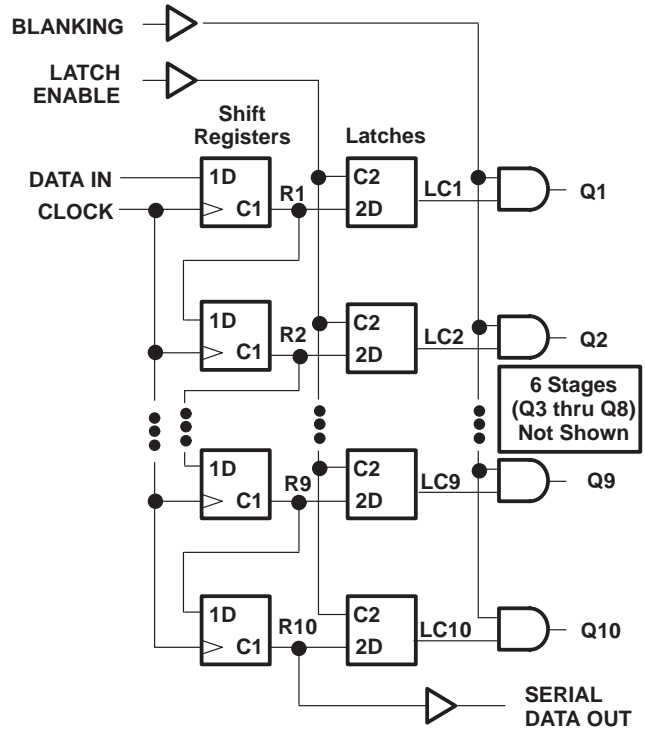
logic symbol†

† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the N package.

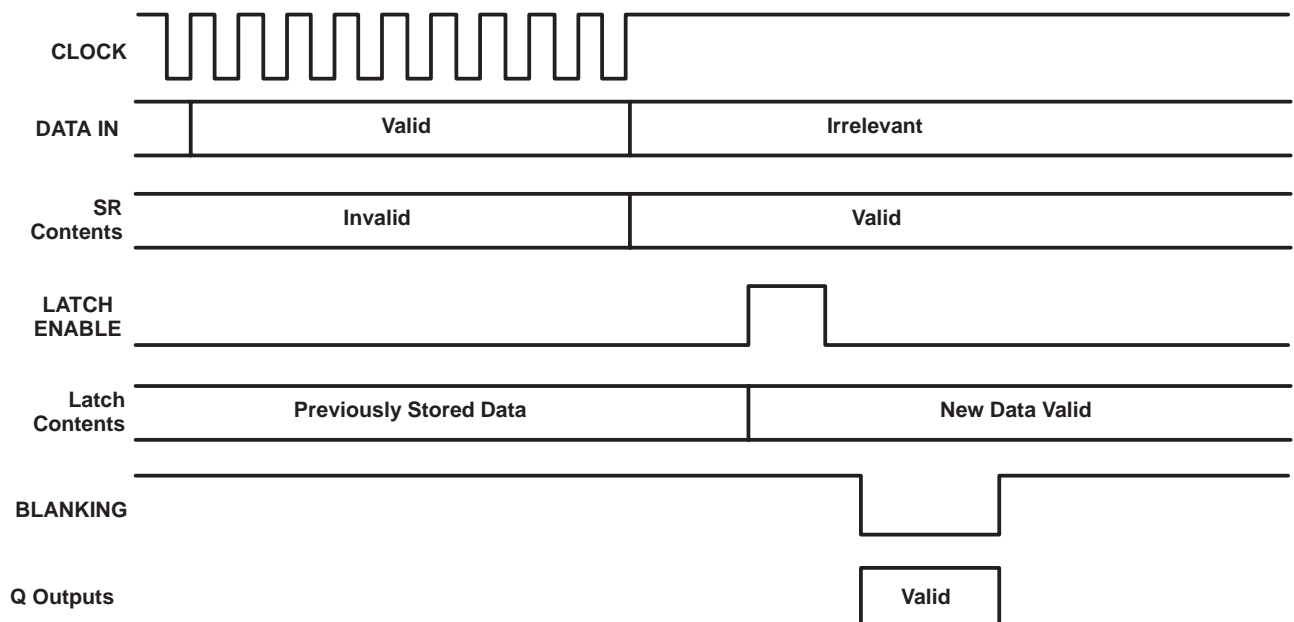## logic diagram (positive logic)

FUNCTION TABLE

FUNCTION	CONTROL INPUTS			SHIFT REGISTERS R1 THRU R10‡	LATCHES LC1 THRU LC10	SERIAL	OUTPUTS Q1 THRU Q10
	CLOCK	LATCH ENABLE	BLANKING				
Load	↑	X	X	Load and shift‡	Determined by LATCH ENABLE§	R10	Determined by BLANKING
	No↑	X	X	No change		R10	Determined by BLANKING
Latch	X	L	X	As determined above	Stored data	R10	Determined by BLANKING
	X	H	X		New data	R10	
Blank	X	X	H	As determined above	Determined by LATCH ENABLE§	R10	All L
	X	X	L			R10	LC1 thru LC10, respectively

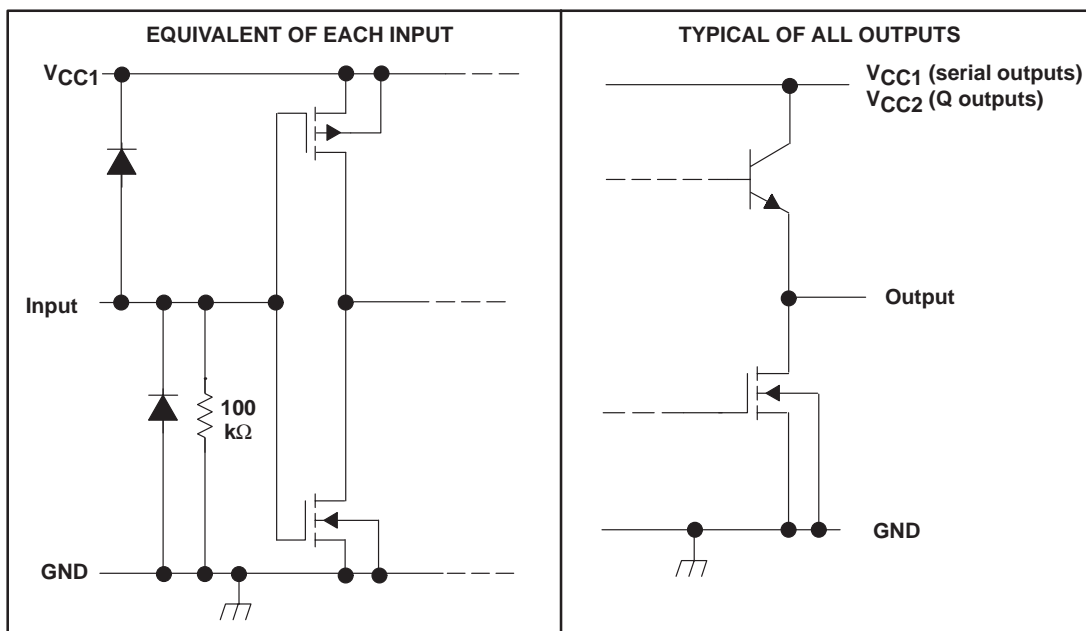H = high level,   L = low level,   X = irrelevant,   ↑ = low-to-high-level transition.
‡ Register R10 takes on the state of R9, R9 takes on the state of R8...R2 takes on the state of R1, and R1 takes on the state of the data input.
§ New data enter the latches while LATCH ENABLE is high. These data are stored while LATCH ENABLE is low.

typical operating sequence

CLOCK		
DATA IN	Valid	Irrelevant
SR Contents	Invalid	Valid
LATCH ENABLE		
Latch Contents	Previously Stored Data	New Data Valid
BLANKING		
Q Outputs		Valid

schematics of inputs and outputs

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Logic supply voltage, V_{CC1} (see Note 1) .... 18 V
Driver supply voltage, V_{CC20} .... 70 V
Output voltage, V_O .... 70 V
Input voltage range, V_I .... −0.3 V to V_{CC1} + 0.3 V
Continuous total power dissipation .... See Dissipation Rating Table
Operating free-air temperature range, T_A: TL4810B .... 0°C to 70°C
                            TL4810BI .... −40°C to 85°C
Storage temperature range, T_{stg} .... −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds .... 260°C

NOTE 1: Voltage values are with respect to GND.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING
DW	1125 mW	9.0 mW/°C	720 mW	585 mW
N	1150 mW	9.2 mW/°C	736 mW	598 mW

recommended operating conditions

PARAMETER		TL4810B MIN	TL4810B MAX	TL4810BI MIN	TL4810BI MAX	UNIT
Supply voltage, V_{CC1}		4.75	15.75	4.75	15.75	V
Supply voltage, V_{CC2}		5	60	5	60	V
High-level input voltage, V_{IH}	$V_{CC1} = 5$ V	3.5	5.3	3.5	5.3	V
	$V_{CC1} = 15$ V	13.5	15.3	13.5	15.3	
Low-level input voltage, V_{IL}		−0.3†	0.8	−0.3†	0.8	V
Continuous high-level output current, I_{OH}			−25		−25	mA
Operating free-air temperature, T_A		0	70	−40	85	°C

† The algebraic convention, in which the less positive (more negative) limit is designated as minimum, is used in this data sheet for logic voltages only.

electrical characteristics over recommended operating free-air temperature range, V_{CC1} = 5 V to 15 V, V_{CC2} = 60 V, GND = 0 (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		TL4810B MIN	TL4810B TYP‡	TL4810B MAX	TL4810BI MIN	TL4810BI TYP‡	TL4810BI MAX	UNIT
V_{OH}	High-level output voltage	Q outputs	$I_{OH} = -25$ mA		57.5	58		57.5	58		V
		SERIAL DATA OUT	$V_{CC1} = 5$ V,	$I_{OH} = -100$ µA	4	4.5		4	4.5		
			$V_{CC1} = 15$ V,	$I_{OH} = -100$ µA	14	14.7		14	14.7		
V_{OL}	Low-level output voltage	Q outputs	$I_{OL} = 1$ µA,	BLANKING at V_{CC1}		0.5	1		0.5	1	V
		SERIAL DATA OUT	$V_{CC1} = 5$ V,	$I_{OL} = 100$ µA		0.05	0.1		0.05	0.1	
			$V_{CC1} = 15$ V,	$I_{OL} = 100$ µA		0.02	0.1		0.02	0.1	
I_{OL}	Low-level Q output current (pulldown current)		$V_O = 60$ V, $T_A = $ MIN to 70°C	BLANKING at V_{CC1},	2.5	3.7		2.5	3.7		mA
			$V_O = 60$ V, $T_A = 85$°C	BLANKING at V_{CC1},				2			
$I_{O(off)}$	Off-state output current		$V_O = 0$, $T_A = $ MAX	BLANKING at V_{CC1},		−1	−15		−1	−15	µA
I_H	High-level input current		$V_I = V_{CC1}$			30	50		30	50	µA
I_{CC1}	Supply current from V_{CC1}		All inputs at 0 V, One Q output high	$V_{CC1} = 5$ V		10	50		10	50	µA
				$V_{CC1} = 15$ V		10	100		10	100	
			All inputs at 0 V, All outputs low	$V_{CC1} = 5$ V		10	50		10	50	
				$V_{CC1} = 15$ V		10	100		10	100	
I_{CC2}	Supply current from V_{CC2}		All outputs low			0.5	1		0.5	1	mA
			All outputs high,	$T_A = 0$°C to MAX		2.7	4		2.7	4	
			All outputs high,	$T_A = -40$°C						5	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at $T_A = 25$°C, except for I_O.

timing requirements over recommended operating free-air temperature range

		$V_{CC1} = 5$ V MIN	$V_{CC1} = 5$ V MAX	$V_{CC1} = 15$ V MIN	$V_{CC1} = 15$ V MAX	UNIT
$t_{w(CKH)}$	Pulse duration, CLOCK high	250		50		ns
$t_{w(LEH)}$	Pulse duration, LATCH ENABLE high	250		50		ns
$t_{su(D)}$	Setup time, DATA IN before CLOCK↑	125		25		ns
$t_{h(D)}$	Hold time, DATA IN after CLOCK↑	125		25		ns
$t_{d(CKH-LEH)}$	Delay time, CLOCK↑ to LATCH ENABLE high	125		25		ns

switching characteristics, V_{BB} = 60 V, $T_A = 25$°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{pd}	Propagation delay time, LATCH ENABLE to Q outputs	$V_{CC1} = 5$ V		1		µs
		$V_{CC1} = 15$ V		0.5		

PARAMETER MEASUREMENT INFORMATION
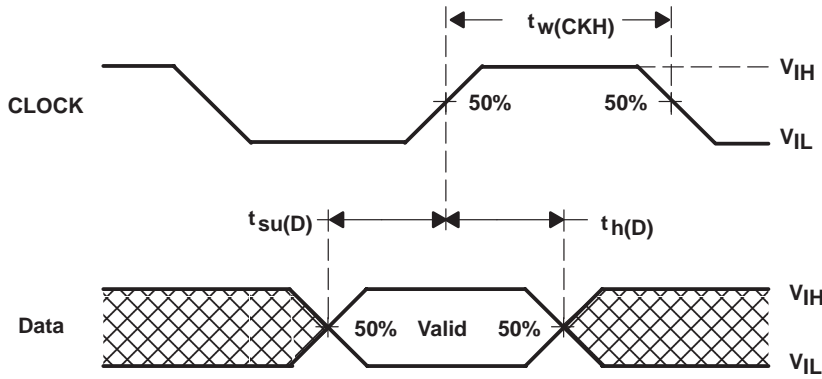
Figure 1. Input Timing
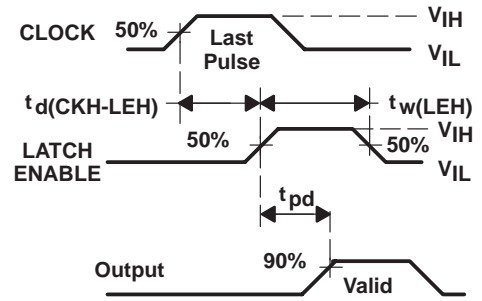
Figure 2. Output Switching Times
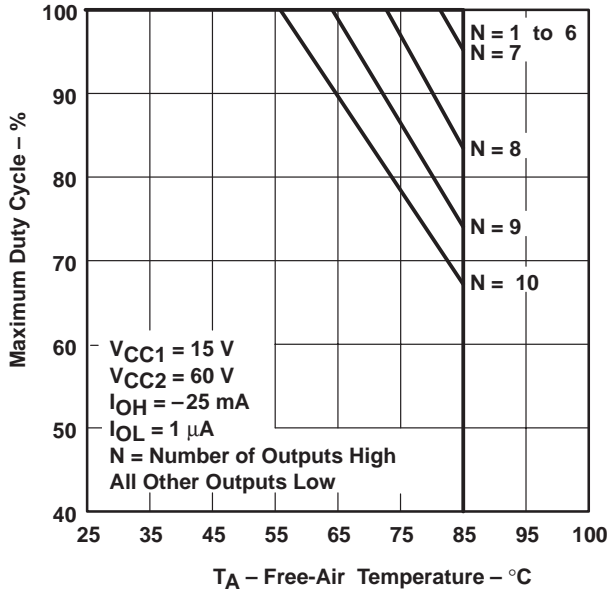
THERMAL INFORMATION

DW PACKAGE DUTY CYCLE
vs
FREE-AIR TEMPERATURE

$V_{CC1} = 15$ V
$V_{CC2} = 60$ V
$I_{OH} = -25$ mA
$I_{OL} = 1$ μA
N = Number of Outputs High
All Other Outputs Low

Figure 3

N PACKAGE DUTY CYCLE
vs
FREE-AIR TEMPERATURE

$V_{CC1} = 15$ V
$V_{CC2} = 60$ V
$I_{OH} = -25$ mA
$I_{OL} = 1$ μA
N = Number of Outputs High
All Other Outputs Low

Figure 4

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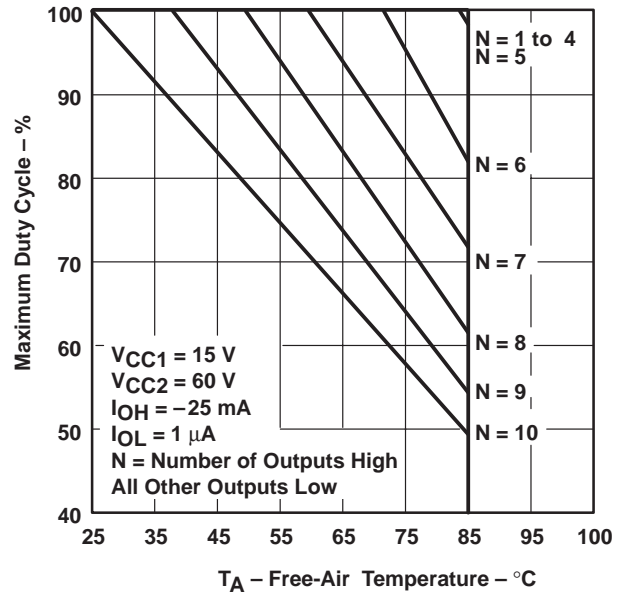**IMPORTANT NOTICE**

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